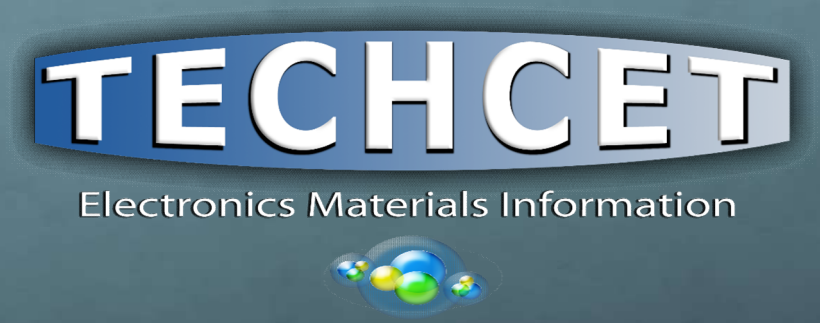


2017 Photoresists, Extensions, & Ancillaries Critical Materials Report™

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June 2017

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